

PRODUCT DATA SHEET

CW-301

Water-Soluble Cored Wire Solder

Introduction

CW-301 Wire Solder is cored with a high-reliability water-soluble flux that is compatible with Indium Corporation's full line of Pb-free soldering materials. It provides excellent solder spread with minimal smoking and low odor. The fast wetting speed is beneficial in minimizing rework cycle time which is typically longer with Pb-free solders.

Features

- Optimized for use with Sn/Pb and Pb-free assembly and rework processes
- Excellent cleanability with cold water
- Fast and excellent wetting to common Pb-free surface finishes including: ImSn, ENIG, OSP, and ImAg
- Minimal spattering and low odor
- Resistant to charring

Product Description

| | |
|---------------------------------|---|
| IPC J-STD-004B Classification | ORH1 |
| Acid Value (mgKOH/gram of flux) | 57 |
| Rosin-Containing | No |
| Halide Content % | 3.0 |
| Smoke | Medium |
| Odor | Mild |
| Color | Amber |
| IPC J-STD-006 Compliance | Indium Corporation impurity levels conform to or exceed IPC J-STD-006 |
| Compatible Alloys | All common and specialty alloys† |
| Copper Mirror IPC J-STD-004B | Pass |
| Copper Corrosion IPC J-STD-004B | Pass |
| SIR J-STD-004B* | Pass |
| Electromigration J-STD-004B* | Pass |

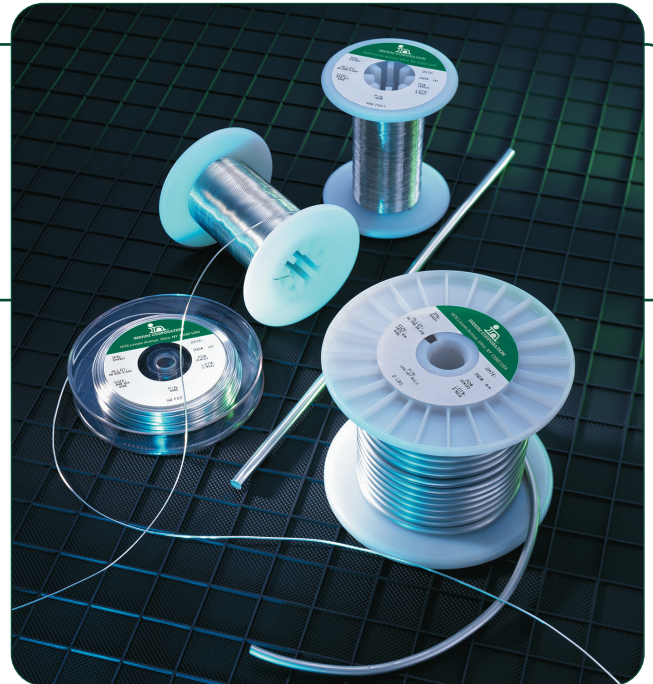
† Common Alloys: SAC305; SACm®0510; Sn995; SAC105; SAC0307; SAC387; 96.5Sn/3.5Ag; 95Sn/5Sb; Indalloy®227; Indalloy®254; 63Sn/37Pb; 60Sn/40Pb; 93.5Pb/5Sb/1.5Ag; 43Sn/43Pb/14B, and all similar alloys.

* Data available upon request.

Wire Diameters

| Wire Solder Length Per Spool | |
|----------------------------------|-----------------------------|
| Wire Diameter | 96.5Sn/3.0Ag/0.5Cu (SAC305) |
| 0.010" ± .002" (.254mm ± .051mm) | 1,950ft (595m) |
| 0.015" ± .002" (.381mm ± .051mm) | 2,025ft (618m) |
| 0.020" ± .002" (.508mm ± .051mm) | 1,140ft (347m) |
| 0.032" ± .002" (.813mm ± .051mm) | 445ft (136m) |

Values are only approximate. Actual lengths may vary.



Residue Removal

The flux in **CW-301** is formulated for use in water-wash assembly processes. The post-soldering flux residue should be removed as soon as possible after soldering. The residue may be readily cleaned in conventional equipment without the use of saponifiers or detergents. It is important that the cleanliness of boards and components are thoroughly checked after soldering and cleaning. Deionized water is recommended for final rinse.

Shelf Life

| | Warranted | Practical* |
|------------------|------------------|------------|
| Tin-Lead Alloys | 3 years from DOM | Indefinite |
| Lead-Free Alloys | 3 years from DOM | Indefinite |
| >85% High-Lead | 2 years from DOM | Indefinite |

*When stored at less than 40°C and less than 80% RH

When stored in a cool, dry environment, there is no reason that Indium Corporation's **CW-301** cannot retain its intended soldering properties for many years. The main causes of degraded cored wire reflow performance are the buildup of a thick oxide layer on the surface of the wire, caused by prolonged exposure to higher than normal temperature and humidity conditions, or the buildup of lead carbonate on high-lead (>85%) alloy-cored wire shipped or stored under very high humidity conditions.

From One Engineer To Another®



Form No. 98141 (A4) R6

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Copper Mirror

The J-STD-004B copper mirror test is performed per IPC-TM-650 method 2.3.32. To be classified as an "L" type flux, there should be no complete removal of the mirror surface. **CW-301** shows complete removal of the copper mirror and, therefore, is classified as an "H" flux, type "ORH0."



Technical Support

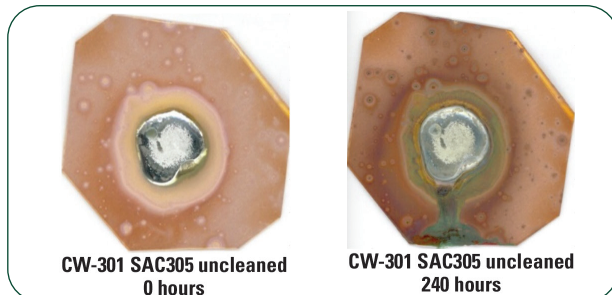
Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Materials Science as it applies to the electronics and semiconductor sectors, Technical Support Engineers provide expert advice in solder properties, alloy compatibility and selection of solder preforms, wire, ribbon, and paste. Indium Corporation's Technical Support Engineers provide rapid response to all technical inquiries.

Safety Data Sheets

Please refer to the SDS document within the product shipment, or contact our local team to receive a copy.

Copper Corrosion

Copper corrosion is tested per IPC-TM-650 method 2.6.15. This test gives an indication of visible reactions that take place between the flux residue after soldering and copper surface finishes. In particular, green copper corrosion (formed as copper-chloride) should not be seen. While green copper chloride is clearly not present, the flux did turn the copper somewhat blue, indicating a reaction product. However, since the residue from this flux is designed to be removed with water and should not be left on the board for 240 hours, this reaction product should not be a concern.



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All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

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